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- 3-State Outputs Drive Bus Lines Directly
- Encodes 8 Data Lines to 3-Line Binary (Octal)
- Applications Include:

 N-Bit Encoding
 Code Converters and Generators
- Typical Data Delay . . . 15 ns
- Typical Power Dissipation . . . 60 mW

description

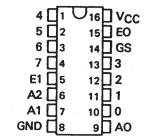
These TTL encoders feature priority decoding of the inputs to ensure that only the highest-order data line is encoded. The 'LS348 circuits encode eight data lines to three-line (4-2-1) binary (octal). Cascading circuitry (enable input E1 and enable output E0) has been provided to allow octal expansion. Outputs A0, A1, and A2 are implemented in three-state logic for easy expansion up to 64 lines without the need for external circuitry. See Typical Application Data.

FUNCTION TABLE

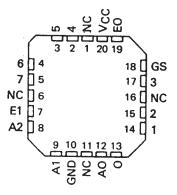
	INPUTS									Ol	JTPU	TS			
EI	0	1	2	3	4	5	6	7	A2 A1 A0 GS E						
Н	Х	Х	Χ	Х	Χ	X	X	Х	Z	Z	Z	Н	Н		
L	Н	Н	Н	Н	Н	Н	Н	Н	z	Z	Z	н	L		
L	Х	Х	Х	Х	Х	Χ	Х	L	L	L	L	L	н		
L	Х	Х	X	Х	Х	Х	L	Н	L	L	Н	L	н		
L	Х	Х	Χ	X	Х	L	Н	Н	L	Н	L	L	н		
L	Х	Х	Χ	Х	L	Н	Н	Н	L	Н	Н	L	н		
L	Ý	Х	Х	L	Н	Н	Н	Н	н	L	L	L	н		
L	Х	Х	L	Н	Н	Н	Н	Н	н	L	н	L	н		
L	Х	L	Н	H	Н	Н	Н	Н	н	Н	L	L	н		
L	L	Н	Н	Н	H	Н	Н	Н	Н	Н	Н	L	н		

H = high logic level, L = low logic level, X = irrelevant

SN54LS348 . . . J OR W PACKAGE SN74LS348 . . . D OR N PACKAGE (TOP VIEW)

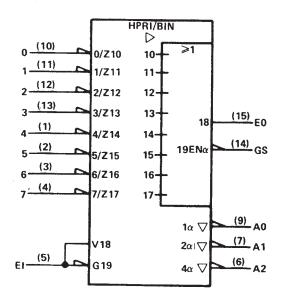


SN54LS348 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

logic symbol[†]



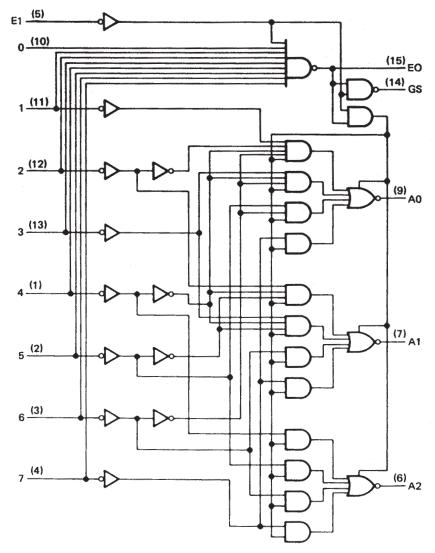
[†]This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.



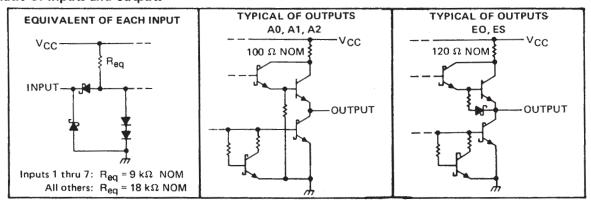
Z = high-impedance state

logic diagram (positive logic)



Pin numbers shown are for D, J, N, and W packages.

schematic of inputs and outputs





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)	
Operating free-air temperature range	SN54LS348
	SN74LS348
Storage temperature range	

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

		SN54LS348			SN74LS348			
		MIN	NOM	MAX	MIN	NOM	MAX	TINU
Supply voltage, V _{CC}		4.5	5	5.5	4.75	5	5,25	V
High-level output current, IOH	A0, A1, A2			-1			-2.6	mA
mightever or that carrents TOH	EO, GS			-400			-400	μА
Low-level output current, IOI	A0, A1, A2			12			24	mA
Fow-level on that carrent, 10F	EO, GS			4			8	mA
Operating free-air temperature, TA		-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER		TEST CO	12	154LS3	148	SN74LS348			UNIT	
	TAKAMETEN		TEST CONDITIONS			TYP‡	MAX	MIN	TYP‡	MAX	UNII
VIH	High-level input voltage				2			2			V
V _{1L} Low-level input voltage						**	0.7			0.8	V
VIK	Input clamp voltage		V _{CC} = MIN,	I ₁ = -18 mA			-1.5			-1.5	V
High-level		A0, A1, A2	V _{CC} = MIN, V _{IH} = 2 V,	I _{OH} = -1 mA	2.4	3.1		2,4	3.1		v
· On	output voltage	EO, GS		$I_{OH} = -2.6 \text{ mA}$ $I_{OH} = -400 \mu\text{A}$	2.5	3.4		2.7	3.4		ľ
Low-level	A0, A1, A2	V _{CC} = MIN,	I _{OL} = 12 mA		0.25	0.4		0.25	0.4		
			V _{1H} = 2 V,	OL = 24 mA			_		0.35	0.5] _v
0.2	Output voltage	EO, GS	VIL = VILmax	1 _{OL} = 4 mA		0.25	0.4		0.25	0.4] *
			ALE ALEMAX	I _{OL} = 8 mA					0.35	0.5	
loz	Off-State (high-impedance	A0, A1, A2	$V_{CC} = MAX$,	V _O = 2.7 V			20			20	μА
- UZ	state) output current	,,,,,,	V _{IH} = 2 V	V _O = 0.4 V			-20			-20	μΑ
ł _I	Input current at maximum	Inputs 1 thru 7	VCC = MAX, VI = 7 V				0.2			0.2	
-1	input voltage	All other inputs	VCC - MAX,	V - / V			0.1			0.1	mA
Ιн	High-level input current	Inputs 1 thru 7	V _{CC} = MAX,	V 27V			40			40	
30	gir tovor tripat carrent	All other inputs	ACC - MAY	V - 2.7 V			20			20	μA
HL	Low-level input current	Inputs 1 thru 7	V _{CC} = MAX,	V. = 0.4.V			-0.8			-0.8	
11	=500 lover input current	All other inputs	ACC = MYY	V - 0.4 V		,	-0.4			-0.4	mA
IOS Short-circuit output current §		Outputs A0, A1, A2			-30		-130	-30		-130	
		Outputs EO, GS	V _{CC} = MAX		-20		-100	-20		-100	mA
Icc	Supply current		V _{CC} = MAX,	Condition 1		13	25		13	25	
ICC Supply current			See Note 2	Condition 2		12	23		12	. 23	mA

[†]For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: ICC (condition 1) is measured with inputs 7 and EI grounded, other inputs and outputs open. ICC (condition 2) is measured with all inputs and outputs open.



 $^{^{\}ddagger}$ All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}$ C.

[§]Not more than one output should be shorted at a time.

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switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ} \text{ C}$

PARAMETER [†]	FROM (INPUT)	TO (OUTPUT)	WAVEFORM	TEST CONDITIONS	MIN	TYP	MAX	UNIT
ФLН	1 thru 7	A0, A1, or A2	In-phase		111	11	17	ns
tPHL.	1 11114 /	A0, A1, 01 A2	output	C. = 45 = 5		20	30	113
ФLН	1 thru 7	C _L = 45 pF,			23		ns	
tPHL	i thru /	A0, A1, or A2	output	R _L = 667 Ω,		23	35	113
tPZH	EI	A0, A1, or A2	See Note 3			25	39	ns
ΨZL] '	70, 71, 01 72				24	41] ""
tPLH	0 thru 7	EO	Out-of-phase			11	18	ns
tPHL	O and /	output	output			26	40	
tPLH	0 thru 7	GS	In-phase	C. = 15 pF		38	55	ns
tPHL	O and /		output	CL = 15 pF		9	21	1 ""
tPLH	EI	GS	In-phase	R _L = 2 kΩ, See Note 3		11	17	
tPHL	1 -	43	output	See Note S		14	36	ns
ФLН	EI	EO	In-phase			17	26	
tPHL	1 "		output	:		25	40	ns
tPHZ	EI	A0, A1, or A2		CL = 5 pF		18	27	
ヤLZ] -'	70, 71, 01 72		R _L = 667 Ω		23	35	ns

[†] tpLH = propagation delay time, low-to-high-level output

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

TYPICAL APPLICATION DATA

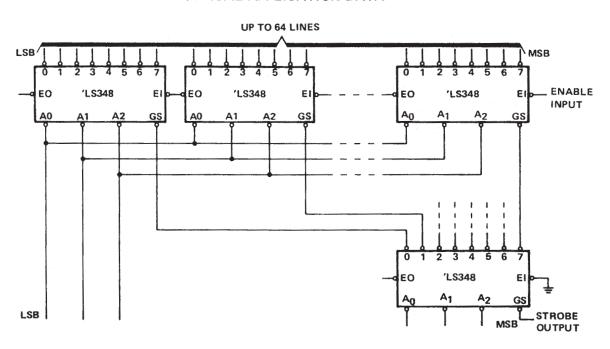


FIGURE 1-PRIORITY ENCODER WITH UP TO 64 INPUTS.



tpHL = propagation delay time, high-to-low-level output

tpzH = output enable time to high level

tpzL = output enable time to low level

tpHZ = output disable time from high level

tpLZ = output disable time from low level

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PACKAGE OPTION ADDENDUM





PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
JM38510/36002B2A	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
JM38510/36002BEA	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SN54LS348J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SN74LS348D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS348DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS348DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS348DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS348DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS348DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS348N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS348N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS348NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS348NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS348NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS348NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54LS348FK	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
SNJ54LS348J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SNJ54LS348W	OBSOLETE	CFP	W	20		TBD	Call TI	Call TI

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.



PACKAGE OPTION ADDENDUM

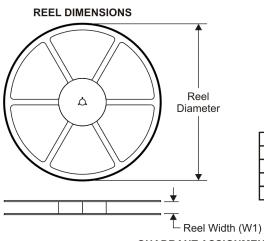
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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

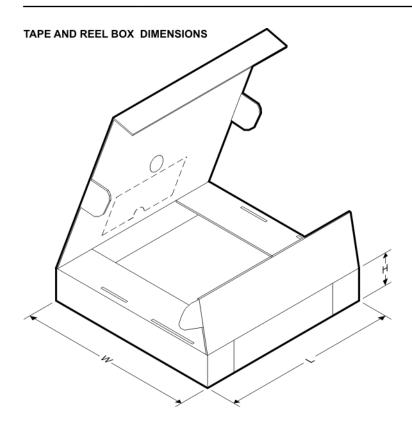
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS348DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LS348NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1





*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS348DR	SOIC	D	16	2500	333.2	345.9	28.6
SN74LS348NSR	SO	NS	16	2000	346.0	346.0	33.0

MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



W (R-GDFP-F20)

CERAMIC DUAL FLATPACK

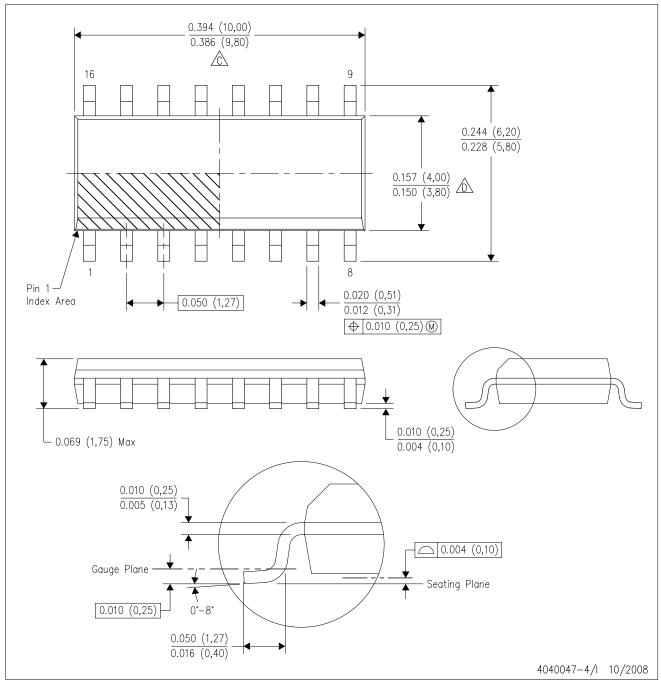


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within Mil-Std 1835 GDFP2-F20



D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AC.



D(R-PDSO-G16)



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Refer to IPC7351 for alternate board design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC—7525
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.

